



AO8810

Common-Drain Dual N-Channel Enhancement Mode Field Effect Transistor

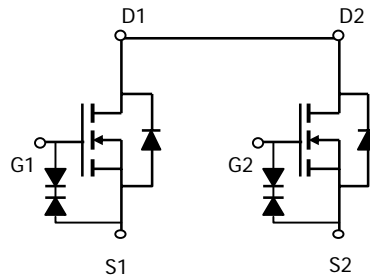
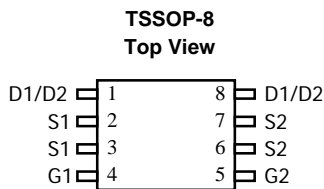


General Description

The AO8810/L uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected. *AO8810 and AO8810L are electrically identical.*
-RoHS Compliant
-AO8810L is Halogen Free

Features

- V_{DS} (V) = 20V
- $I_D = 7$ A ($V_{GS} = 4.5V$)
- $R_{DS(ON)} < 20m\Omega$ ($V_{GS} = 4.5V$)
- $R_{DS(ON)} < 21m\Omega$ ($V_{GS} = 4.0V$)
- $R_{DS(ON)} < 22m\Omega$ ($V_{GS} = 3.1V$)
- $R_{DS(ON)} < 24m\Omega$ ($V_{GS} = 2.5V$)
- $R_{DS(ON)} < 32m\Omega$ ($V_{GS} = 1.8V$)
- ESD Rating: 2000V HBM



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current ^A	$T_A=25^\circ C$	7	A
	$T_A=70^\circ C$	5.7	
Pulsed Drain Current ^B	I_{DM}	30	
Power Dissipation ^A	$T_A=25^\circ C$	1.5	W
	$T_A=70^\circ C$	1	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units	
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	$t \leq 10s$	64	83	$^\circ C/W$
		Steady-State	89	120	
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	53	70	$^\circ C/W$	

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
B _V DSS	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =16V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±4.5V V _{DS} =0V, V _{GS} =±8V			±1 ±10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250μA	0.4	0.6	1	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	30			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =7A T _J =125°C	12 18	16.5 23	20 28	mΩ
		V _{GS} =4.0V, I _D =7A	12	17	21	mΩ
		V _{GS} =3.1V, I _D =6.5A	13	18	22	mΩ
		V _{GS} =2.5V, I _D =5.5A	14	20	24	mΩ
		V _{GS} =1.8V, I _D =5A	16	24	32	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =7A		29		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.76	1	V
I _S	Maximum Body-Diode Continuous Current				2.5	A
DYNAMIC PARAMETERS						
C _{ISS}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, f=1MHz		1160		pF
C _{OSS}	Output Capacitance			187		pF
C _{RSS}	Reverse Transfer Capacitance			146		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		1.5		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =7A		16		nC
Q _{gs}	Gate Source Charge			0.8		nC
Q _{gd}	Gate Drain Charge			3.8		nC
t _{D(on)}	Turn-On Delay Time	V _{GS} =5V, V _{DS} =10V, R _L =1.35Ω, R _{GEN} =3Ω		6.2		ns
t _r	Turn-On Rise Time			12.7		ns
t _{D(off)}	Turn-Off Delay Time			51.7		ns
t _f	Turn-Off Fall Time			16		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =7A, dI/dt=100A/μs		17.7		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =7A, dI/dt=100A/μs		6.7		nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

D: The static characteristics in Figures 1 to 6,12,14 are obtained using <300 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

Rev 7 : Feb. 2008

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

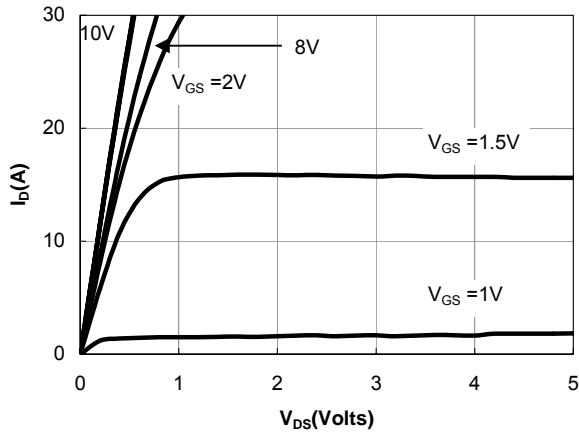


Figure 1: On-Regions Characteristics

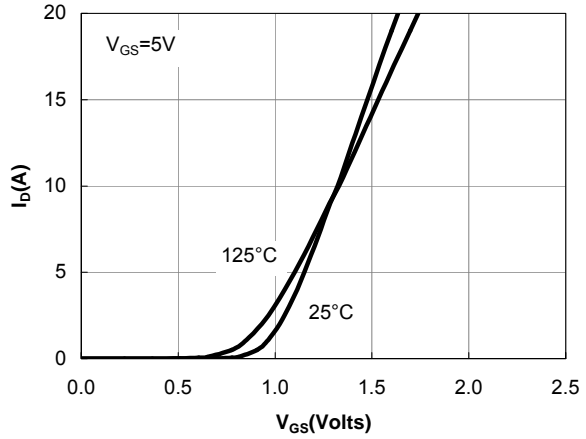


Figure 2: Transfer Characteristics

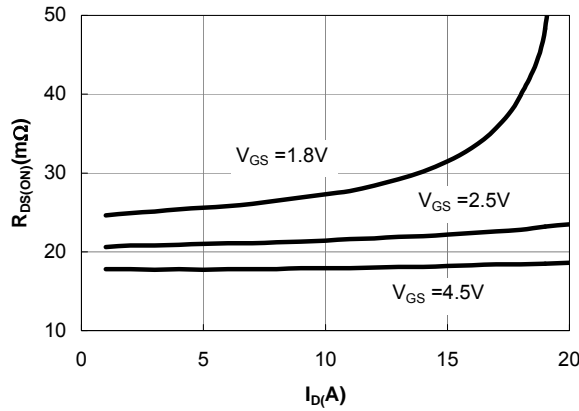


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

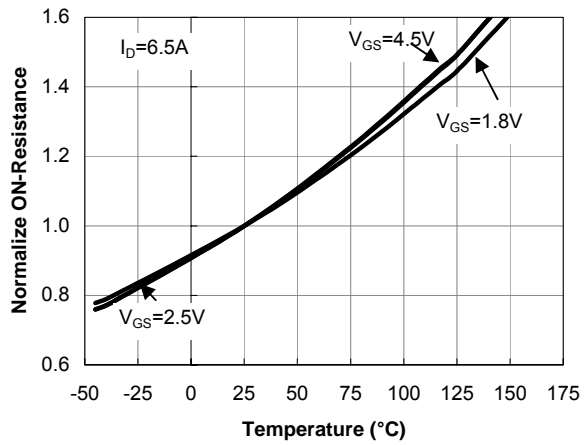


Figure 4: On-Resistance vs. Junction Temperature

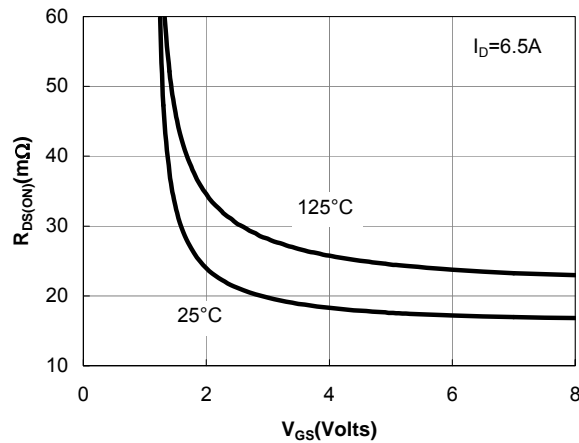


Figure 5: On-Resistance vs. Gate-Source Voltage

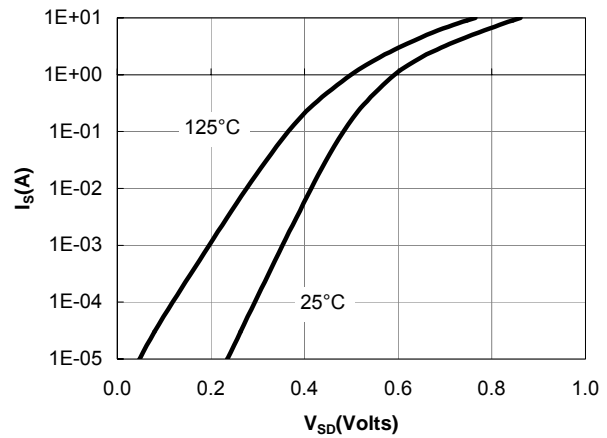


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

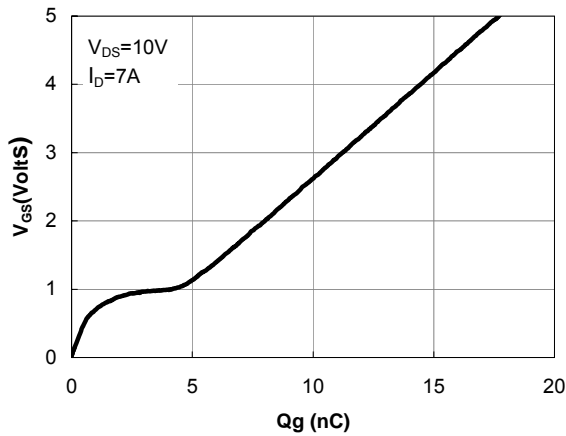


Figure 7: Gate-Charge Characteristics

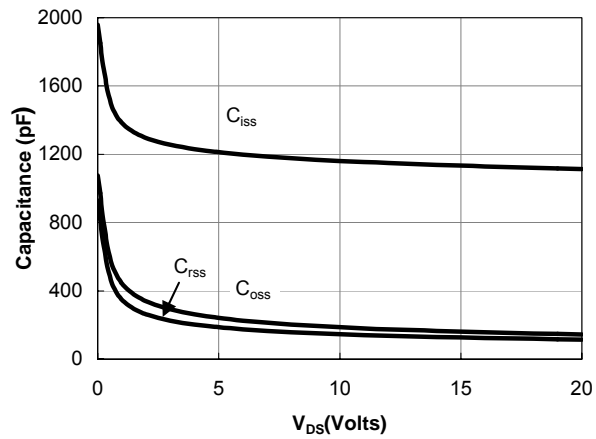


Figure 8: Capacitance Characteristics

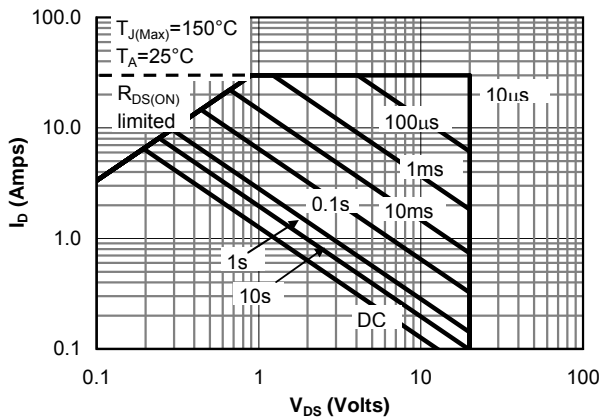


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

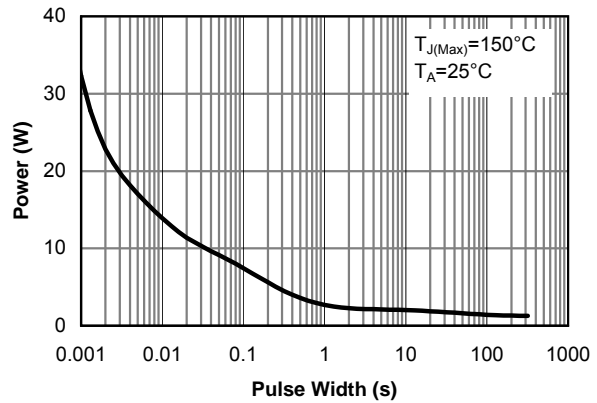


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

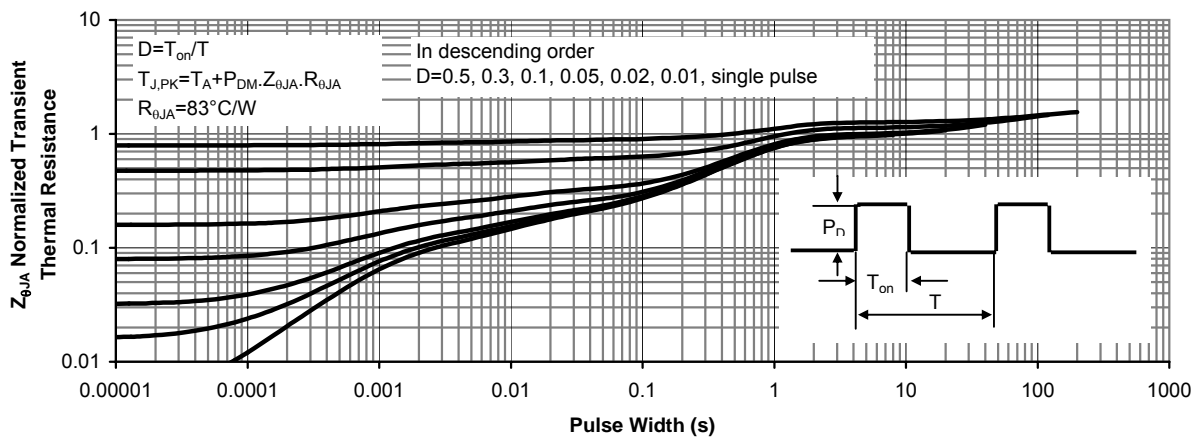


Figure 11: Normalized Maximum Transient Thermal Impedance